Microdis CONTACT **ELECTROMECHANICAL** MICRODIS ELECTRONICS Innovation & Reliability



Temperature range: -200°C to 1200°C

HARNESS MAKING, ASSEMBLING, MACHINES AND TOOLS

Halogen free/flame-resistant/lead-free

solderless terminals and splices

Harness making Crimping all typical connectors,

half or full automatic process

from AWG32(0.05 mm2) up to AWG8 (8.00 mm2)

Benchtop Crimping & Stripping

Design-in support - well trained engineers are providing high

Sample supply and product info - high level and many

Cutting to Length & Stripping Full Process Crimping

quality service

possibilities

years of experience

Cutting and stripping

Lead free tin plating

Machines for:

Marking

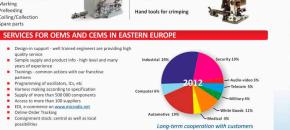
Prefeeding

Spare parts

Coiling/Collection







Strips and cables

Customized harness

Applicators -

Presses

connectors

Other tools

& applicators

Applicators for:

Testing tools

for RAST connectors

JST, LEAR, TYCO, JAE, FCI

for all types of

 Trainings - common actions with our franchise Programming of oscillators, ICs, etc. Harness making according to specification Supply of more than 500 000 components Access to more than 100 suppliers ■ EDI. e-commerce on www.microdis.net Online Order Tracking Consignment stock: central as well as local covering all industrial segments Supply of small quantities by catalogue distribution

Romania@microdis.net ussia@microdis.net Czech@microdis.net Estonia@microdis.net Slovakia@microdis.net ovenia@microdis.net Turkey@microdis.net Lithuania@microdis.net Jkraine@microdis.net crodis.de@microdis.net

eading in Eastern Europe as technical broadline distributor of Microdis electronic components, logistic provider and always reliable partner for suppliers and customers.

Innovation & Reliability



- Franchise Distribution for a selected Baltic (LT, LV, EST) 6.3 number of manufacturers
- Special Mass Market Distribution by Internet and Catalogue
- Network Partnership with suppliers and customers







DEVELOPMENT STEPS OF THE MICRODIS ELECTRONICS GROUP

- 1989 Foundation of the companies in Hungary and Germany 1990 Foundation of sales companies in Poland and Slovakia
- First deliveries to the industry
- 1992 Foundation of LSB Electronics later renamed to Microdis Plus Poland
- Restructuring from retail to distribution
- 1993 Foundation of Microdis KFT in Hungary
- 1995 Consolidation of all companies within the Eurodis Microdis Holding AG in Switzerland (60% Eurodis [later Eurodis Electron PLC] and 40% Microdis) Foundation of a subsidiary in Czech Republic
- 2000 Europartners Consultants proclaimed Eurodis Microdis No. 1 in Poland and
- No. 3 in Hungary. Start of catalogue distribution 2003 Microdis sells its 40% shares of the Eurodis Microdis Electronics AG to
- Eurodis Electron PLC and takes over entirely Eurodis Microdis Electronics in Germany
- 2006 Microdis obtained ISO 9001:2000 Certification
- 2007 Foundation of Microdis in Ukraine
- 2008 Foundation of Microdis in Latvia
- 2009 Foundation of Microdis in Bulgaria 2010 Microdis Group obtains ISO 9001/2008 Certification
- 2011 Foundation of Microdis Components Elektronik in Turkey (Istanbul)
- 2012 Logistic Center moved to the acquired building in Hockenheim, Germany

www.microdis.net www.microdis.net www.microdis.net www.microdis.net



State of the art GPS/Glonass/Galileo and GSM/UMTS modules based on the latest u-blox7 technology MAX, AMY, NEO, LEA and LEON, LISA families Modules are qualified for in vehicle use (ISO16750) Highest class of navigation features

High performance, ultrafast acquisition (<1s) Low power consumption: 5mA/3V@1Hz Position accuracy (CEP, SBAS): 2.0m High in-band jamming immunity

Jammer detection Assisted GPS: three aiding options for fast start Direct cooperation with GSM/UMTS modules PPP support (Precise Point Positioning) - accuracy <1m(2D.R50) Dedicated modules for timing, RAW data (LEA-6T, NEO-6T) Miniature modules with built-in antenna (UC530M)



Miniature GPS+Glonass module with built-in antenna (9.6x14.0x1.95mm)

WIRELESS ACCESSORIES







GSM & UMTS PRODUCTS

High performance GSM, UMTS and CDMA modules

Navigation without GPS, based on GSM network eCall ready products with in-band modem Available in compact, SMT form factors



Built-in Assisted GPS client to support GPS modules

LISA - GSM/UMTS/HSPA+

Extremely small footprint (33.2x22.4mm)

HSPA+ (21.1Mb/s), HSUPA (5.76Mb/s)

Low power (<1.2 mA in 3G idle mode)

3G bands: 800/850/900/1700/1900/2100MHz

The use of u-blox modules does not lead to consequences from

infringement of patents and copyrights.

Reliable interconnect products

SIM. MicroSIM & NanoSIM Card Connectors

Memory Card Connectors

Board to board connectors

USB Connectors

Six 3G and four 2G bands support

Wide temp, range (-40°C to +85°C)

LISB 2 O SPI LIART

RIL support

Low power consumption (<0.90mA idle, DRX9)

One PCB design for GSM and UMTS module

Simple integration of u-blox GPS modules

Wide temperature range -40°C to +85°C

GSM/GPRS modules - series LEON & SARA LEON, LISA, SARA are qualified for in vehicle use (ISO16750) LEON & SARA GSM/GPRS modules Embedded TCP/UDP/IP, FTP/HTTP/SMTP stack

FOTA (firmware upgrade over-the-air)*

Small form factor 26.0x16.0x3.0mm

Multiple socket & IP addresses

DTMF support

*available on demand

LISA Series - WCDMA

band support

modules with full 3G

SIM900 GSM/GPRS module:

Wireless M-Bus modules and devices 868MHz and 169MHz

range up to 20km

ISM PRODUCTS

Wide range of modules:

RF modules and modems

Available as complete modules

from simple and cost efficient

up to complex modules with

with integrated transmission stacks AMBER

WIRELESS

designed to be used in metering applications with integrated Wireless M-Bus protocol according to EN 13757-4:2005





Modems in IP65 housing with range up to 1km USB modems for 868MHz & 2.4GHz



Up to 320m Bluetooth range - Class 1



Wi-Fi modules





ISO Cards, Key Fobs, Wrist Bands, **PET laminates**

The most popular standards on the market: 125kHz: EM Marin/Unique/Temic, Philips (Hitag) 13.56MHz: Philips (Mifare), Legic

INDUSTRIAL COMPUTING PRODUCTS



In-vehicle computers and displays Wireless communication: GPS, GSM, WLAN Flexible ignition control, easy adoption to car power-systems High vibration resistance, wide operating temperature Additional IP65 housing

Full HD Digital Signage Solutions Wide range of industrial players designed for 24/7 operation Perfect graphic performance, various video outputs

Panel PCs and fanless box computers for automation industry Compact sizes, low power consumption Many options of I/O interfaces, high reliability

Single, dual, triple and quad display possibility

Embedded OS, watchdog built-in, long life



the rear

IP67 Panel PCs, Industrial displays, Embedded boards Fanless with Intel, VIA and AMD CPUs, RISC Different form factors: FSB, HSB, 3.5", 5.25", PC/104 EPIC, ETX, ITX, XTX, COM, Qseven







inputs, dedicated space for multimedia player mounting at

32 - 65" Large Format Displays with Touchscreen Fanless, great viewing angles and exceptional color clarity. wide range of video and audio

Square and round modules in different sizes LED strips Acrich2 modules Lighttubes

LIGHTING PRODUCTS

SEOUL SEMICONDUCTOR SEOUL

ACRICH2 - supplied directly from 230VAC. Luminous flux of one module up to 1450lm (17.5W)



Z-POWER LED - super bright power LEDs, Efficacy up to 160lm/W SIDE, TOP, CHIP, LAMP, HIGH FLUX LED - available as through hole and SMD, ultrabright, multicolor, infrared, ultraviolet, full-color (RGB)



Japanese Power LEDs, SMD and THT 151lm/W with CCT 5000K Power LEDs with high CRI (up to 95) Special colors for food lighting (meat, fish, dairy and

baked goods) 2000K & 2400K for mood lighting LEDs for automotive market, IR LEDs



Taiwanese cost-effective LEDs Wide portfolio of signalling LEDs Double color (warm + cool) power LEDs Standard form factors 12W-36W (9090) 4-chip power LEDs Power LED matrix modules

Customized solutions

LED modules



SEMICONDITICTOR

High quality semiconductors Transient Voltage Suppressors

Zener and switching diodes Rectifier diodes Rectifier bridges Linear and switching voltage regulators Amplifiers and comparators

Voltage references Industry standards:

78(9)xx, 78(9)Lxx, LM317, LM339, LM358, LM431. LM810. SMAJ, SMBJ, SMCJ, P4KE, P6KE, 1,5KE, BAV, BAS, BAT and many others



Transoptors and MOSFET drivers

High performance infrared optoelectronic devices VDE, UL, NEMKO. ISO9001:2000 certified.

Pin-to-pin equivalents to most typical solutions like TLP12, TLP18, PC817, PC357, MOC30, CNY17, SFH6 and many others available.

Outstanding quality available with short lead time.



Timing & Sensing Devices Programmable Oscillators Customer specified frequency (1.000MHz to 166.000MHz)

sensing crystals

Crystal units/Resonators - kHz and MHz range SAW resonators Oscillators - SPXO, VCXO, TCXO, OCXO, Rubidium Filters - Crystal, SAW RTC Modules Sensors - Gyro, Temperature sensing crystals, Pressure



assembly solutions

Generic connectors

Tact Switches

Snap-in types

12x12mm sizes

10x10mm sizes

available

Encoders

available

(stem color coding)

Surface Mount types

AluLite™ Series - Aluminum connectors

Nim-Camac - Coax and Triax Connectors

UltiMate™ - high performance military connectors

available in 4.5x4.5mm to

available in 2.8x2.4mm to

Sharp and Soft feeling types

Multiple operating force versions

Dust proof & water proof versions

Rotary and slide potentiometers,

Memory and SIM card connectors

Magnetic, MEMS and capacitive

also dedicated for automotive market

industrial and pro-audio types

Multicontrol Devices

Power Switches

Detector switches

Thermal Printers

concore



Push-pull circular connectors and cable

Core Series - Brass connectors

Plastic Series - Plastic connectors Specific Connecors

Disposable - Low cost, high performance connectors SD/HD Camera connectors - Triax or Fiber Optic

ALPS

Wide range of electromechanical solutions



SPRINGCON - spring type RIACON - screw type

PLUGCON - pin strips IDCON - IDC - PCB connectors



CONNECT

relektronik 🛂

Heatsinks Machined extruded

heatsinks Heatsinks for LEDs Extruded heatsinks with mounting

Heatsinks and fan coolers f processors, PGA & BGA components

Cooling aggregates Thermal conductive materials

Cases

Miniature aluminum cases Combination cases Desk consoles and shell cases 19" system cases

Connectors

Hi precision board-to-board connectors IDC connectors D-SUB connectors

heatsinks, cases, front YAG laser engraving





